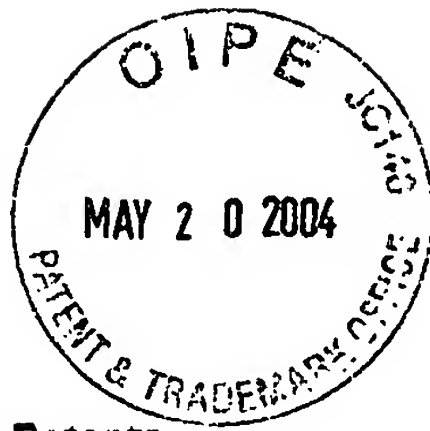


TSMC01-614



September 29, 2003

To: Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Fr: Stephen B. Ackerman, Reg. No. 37,761
28 Davis Ave.
Poughkeepsie, N.Y. 12603

Subject:

Serial No. 10/055,095

01/23/02

C. C. Huang et al

"METHOD TO IMPROVE VIA OR CONTACT
HOLE PROFILE USING AN IN-SITU POLYMER
DEPOSITION AND STRIP PROCEDURE"

GRP. Art. Unit 2829

E. T. Pert

RESPONSE PATENT OFFICE ACTION

Dear Sir;

In response to the Office Action dated September 10, 2003, please amend the identified application for patent as follows:

The commissioner is hereby authorized to charge payment of any additional fees involved with added Claims and the like to Deposit Account No. 19-0033

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450 Alexandria, VA 22313-1450, on February 10, 2004.

George O. Saile, Reg. No. 19,572

Signature

George O. Saile

Date

2/10/04

TSMC01-614

Amendments to the Claims begin on page 3

Remarks begin on page 12.